

ABSTRACT

The present disclosure provides a carrier apparatus, a process chamber, and semiconductor process equipment. The carrier apparatus includes: a support assembly having a carrying surface at a top thereof and further having an introduction passage extending from a bottom of the support assembly to the carrying surface; a conductive assembly extending through the introduction passage and configured to be electrically connected to an electrostatic tray so as to feed an external voltage to an attraction electrode in the electrostatic tray; and a sealing assembly sleeved over an outer side of the conductive assembly and sealingly connected to the conductive assembly, the sealing assembly being connected to the bottom of the support assembly and being in sealing engagement with the support assembly so as to seal an end of the introduction passage located at the bottom of the support assembly. The solution of the present disclosure solves the sealing problem occurring in the process chamber when the electrostatic tray is separated from the carrier apparatus or when a sealing ring ages, thereby improving wafer quality.